

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	2001-585120.NRAN.	DERWENT	OR	OFF	2009/05/04 14:12
L3	12	JP-2001102758-\$.did. jp- 09136943-\$.did. jp- 2003020327-\$.did. jp- 2004149577-\$.did. jp- 2003128877-\$.did. jp- 11269355-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L4	1214517	silica (silicon adj2 (oxide dioxide)) "sio2" "sio.sub.2"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L5	736375	epox\$6 diepox\$6 triepox\$6 polyepox\$6 glycidyl\$ diglycidyl \$ triglycidyl\$ tetraglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L6	20951	(L4 silicate) with (lamellar planar plane flake)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L7	31	motobe-h\$.in. motobe-h\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L8	640	hibino-a\$.in. hibino-a\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L9	55344	ito-k\$.in. ito-k\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L10	9	L7 and L8 and L9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L11	922773	matsushita.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19

L12	22	(L7 L8 L9 L10 L11) and L5 and L6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L13	729284	(surface adj2 area) "ssa" "s.s.a."	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L14	951265	(particle particulate grain) near5 (size diameter micron micrometer nanometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L15	42	(novolak novolac novalak novalac) and L6 and L13 and L14 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L16	7	(L7 L8 L9 L10 L11) and L5 and L6 and L13 and L14	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L17	42	L5 and (novolak novolac novalak novalac) and L6 and L13 and L14 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L18	42	L5 and (novolak novolac novalak novalac) and L6 and L13 and L14 and (((wiring circuit) adj2 board) "pwb" "pcb" "p.w.b." "p.c.b.")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L19	14794	(428/297.4.ccls. 428/413.ccls. 428/414.ccls. 428/415.ccls. 428/416.ccls. 428/417.ccls. 428/418.ccls. 428/901.ccls. 156/325.ccls. 156/326.ccls. 156/327.ccls. 156/330.ccls. 523/440.ccls. 523/443.ccls. 523/466.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L20	168	L19 and L5 and L6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
L21	18	L19 and L5 and L6 and L13 and L14	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19

L22	2	L5.clm. and (novolak novolac novalak novalac).clm. and L6 and L13 and L14 and (((wiring circuit) adj2 board) "pwb" "pcb" "p.w.b." "p.c.b.")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/04 14:19
S25	496814	silicone polysiloxane polyorganosiloxane polydiorganosiloxane organopolysiloxane organosiloxane diorganopolysiloxane siloxane organosilicone	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/14 09:00
S26	317795	curative hardener (cross adj2 linker) crosslinker ((curing hardening (cross adj2 linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/28 14:33
S27	1222941	amine amino diamine diamino triamine triamino polyamine polyamino	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/12 13:13
S28	605176	epox\$6 diepox\$6 triepox\$6 polyepox\$6 glycidyl\$ diglycidyl\$ triglycidyl\$ tetraglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/14 09:01
S34	2	"20060216495".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 12:58
S35	1	2005-152068.NRAN.	DERWENT	OR	OFF	2008/06/19 13:01
S36	0	us20060216495-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:02
S37	2	us-20060216495-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:02
S38	4	JP-2001102758-\$.did. jp-09136943-\$.did. jp-200320327-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:06
S39	6	JP-2001102758-\$.did. jp-09136943-\$.did. jp-200320327-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:07

S40	1133142	silica (silicon adj2 (oxide dioxide)) "sio2" "sio.sub.2"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:08
S41	7070	S40 with (lamellar planar)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:08
S42	692669	epox\$6 diepox\$6 triepox\$6 polyepox\$6 glycidyl\$ diglycidyl \$ triglycidyl\$ tetraglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:09
S43	48	S42 and (novolak novolac novolak novolac) and S41	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:09
S44	684346	(surface adj2 area) "ssa" "s.s.a."	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:10
S45	897248	(particle particulate grain) near5 (size diameter micron micrometer nanometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:11
S46	14	S43 and S44 and S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:11
S47	19518	(S40 silicate) with (lamellar planar plane flake)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:15
S48	185	S47.ab. and S42.ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:15
S49	17	(novolak novolac novalak novolac) and S48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:16

S50	112	(novolak novolac novalak novalac) and S47 and S44 and S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:19
S51	38	(novolak novolac novalak novalac) and S47 and S44 and S45 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:20
S52	30	motobe-h\$.in. motobe-h\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:31
S53	598	hibino-a\$.in. hibino-a\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:31
S54	53474	ito-k\$.in. ito-k\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:32
S55	9	S52 and S53 and S54	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:32
S56	897711	matsushita.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:33
S57	21	(S52 S53 S54 S55 S56) and S42 and S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:34
S58	38	(novolak novolac novalak novalac) and S47 and S44 and S45 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:39
S59	372	(interplanar near3 spacing).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:46

S60	34	S59 and S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:47
S61	109	michigan.as. and lamellar	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:48
S62	26	pinnavaia.in. and S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:49
S63	12	pinnavaia.in. and S42 and S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:50
S64	13	pinnavaia.in. and S42 and S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:51
S65	0	S64 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:54
S66	0	S64 and prepreg	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:55
S67	14458	(S40 silicate) near3 (lamellar planar plane flake layered exfoliat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:56
S68	2846	S67 and S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:56
S69	224	S68 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:56

S70	7206	(S40) near3 (lamellar planar plane flake layered exfoliat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:56
S71	140	S69 and S70	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:57
S72	2	"20060216495".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:01
S73	28	(novolak novolac novalak novalac) and S71	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:12
S74	27	(cresole resol cresol resol) and S71	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:12
S75	357156	curative hardener (cross adj2 linker) crosslinker ((curing hardening (cross adj2 linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:13
S76	20	((phenol phenolic) with S75) and S71	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:13
S77	48	S69 and S70 and (impregnat\$4 prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:14
S78	13	S70.ab. and S44.ab. and S45.ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:17
S79	27004	(S40) near3 (lamellar planar plane flake layered exfoliat\$4 scaly plate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:19

S80	27	S79.ab. and S44.ab. and S45.ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:20
S81	47	S79 same S44 same S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:21
S82	11	(S79 same S44 same S45) and (electronic ((wiring circuit) adj2 board) prepreg impregnat\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:22
S83	2915	S79.ab. S79.ti.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:31
S84	62	S83 and S44 and S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:31
S85	12	S84 and (((wiring circuit) adj2 board) prepreg impregnat\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:39
S86	1879	(S40) near3 (crushed)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:55
S87	364	S86 and S44 and S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:56
S88	119	S87 and (((wiring circuit) adj2 board) prepreg impregnat\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:56
S89	12	"155" and (((wiring circuit) adj2 board) prepreg impregnat\$) and S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:56



S90	36	S87 and (((wiring circuit) adj2 board) prepreg impregnat\$) and S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:57
S91	10	S87 and (((wiring circuit) adj2 board) prepreg impregnat\$) and S42 and (novolak novolac novolak novolac)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:03
S92	10	S87 and (((wiring circuit) adj2 board) prepreg impregnat\$) and S42 and (novolak novolac novolak novolac) and (accelerator catalyst)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:03
S93	439	((S40) near3 (crushed fused)) same S44 same S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:14
S94	70	S93 and (((wiring circuit) adj2 board) prepreg impregnat\$) and S42 and (novolak novolac novolak novolac) and (accelerator catalyst)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:15
S95	47	S93 and (((wiring circuit) adj2 board) prepreg impregnat\$) and S42 and (novolak novolac novolak novolac) and (accelerator catalyst) and (prepreg impregnat\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:16
S96	4	S93 and (prepreg impregnat\$). ab. and S42.ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:18
S97	52	S93 and ((prepreg impregnat\$) same S42)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:19
S98	585	((S40) near3 (crushed fused)) and ((prepreg impregnat\$) same S42)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:20
S99	205	((S40) near3 (crushed)) same (S44 S45)) and S44 and S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:21

S100	5	S99 and ((prepreg impregnat\$ same S42)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:22
S101	1	wo-0151562-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:25
S102	1	2001-611031.NRAN.	DERWENT	OR	OFF	2008/06/19 15:25
S103	9621	428/297.4.ccls. 428/413.ccls. 428/414.ccls. 428/415.ccls. 428/416.ccls. 428/417.ccls. 428/418.ccls. 428/901.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:28
S104	5	S103 and S99	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:28
S105	12	JP-2001102758-\$.did. jp- 09136943-\$.did. jp- 2003020327-\$.did. jp- 2004149577-\$.did. jp- 2003128877-\$.did. jp- 11269355-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 11:37
S106	1182792	silica (silicon adj2 (oxide dioxide)) "sio2" "sio.sub.2"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S107	719270	epox\$6 diepox\$6 triepox\$6 polyepox\$6 glycidyl\$ diglycidyl \$ triglycidyl\$ tetraglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S108	20378	(S106 silicate) with (lamellar planar plane flake)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S109	30	motobe-h\$.in. motobe-h\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S110	613	hibino-a\$.in. hibino-a\$-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15

S111	54635	ito-k\$.in. ito-k\$-\$in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S112	9	S109 and S110 and S111	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S113	914596	matsushita.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S114	21	(S109 S110 S111 S112 S113) and S107 and S108	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:15
S115	711991	(surface adj2 area) "ssa" "s.s.a."	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:16
S116	930289	(particle particulate grain) near5 (size diameter micron micrometer nanometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:16
S117	41	(novolak novolac novalak novolac) and S108 and S115 and S116 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:16
S118	7	(S109 S110 S111 S112 S113) and S107 and S108 and S115 and S116	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:16
S119	41	S107 and (novolak novolac novolac novalac) and S108 and S115 and S116 and ((wiring circuit) adj2 board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:19
S120	41	S107 and (novolak novolac novolac novalac) and S108 and S115 and S116 and (((wiring circuit) adj2 board) "pwb" "pcb" "p.w.b." "p.c.b.")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:19

S122	14677	(428/297.4.ccls. 428/413.ccls. 428/414.ccls. 428/415.ccls. 428/416.ccls. 428/417.ccls. 428/418.ccls. 428/901.ccls. 156/325.ccls. 156/326.ccls. 156/327.ccls. 156/330.ccls. 523/440.ccls. 523/443.ccls. 523/466.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:24
S125	165	S122 and S107 and S108	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:25
S126	17	S122 and S107 and S108 and S115 and S116	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:25
S127	2	S107.clm. and (novolak novolac novalak novalac).clm. and S108 and S115 and S116 and (((wiring circuit) adj2 board) "pwb" "pcb" "p.w.b." "p.c.b.")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/04 12:27

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